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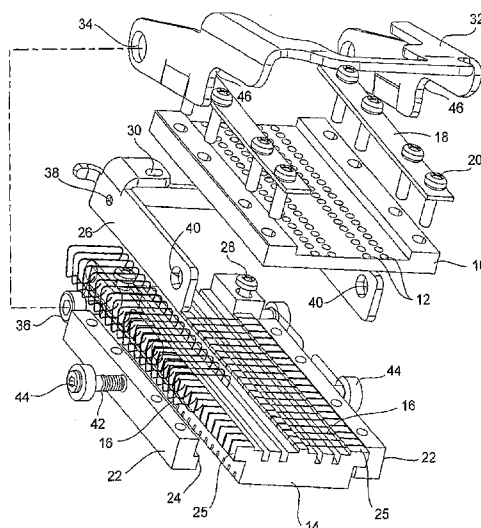
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(54) Title: HIGH TEMPERATURE OPEN ENDED ZERO INSERTION FORCE (ZIF) TEST SOCKET



(57) Abstract: A socket for use in testing packaged integrated circuits having leads depending therefrom includes a first member for receiving the integrated circuit package and having a plurality of holes for receiving leads extending from the package. A second member has a plurality of wire contacts for engaging the leads, the first and second members being arranged to permit relative lateral translation thereof. A support frame includes a first portion which physically engages the first member and a second portion which physically engages the second member. A lever or handle is attached to the second portion and includes a cam surface for engaging a cam follower on the first portion for imparting relative lateral motion between the two members whereby the package leads physically engage wires of the second member.



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